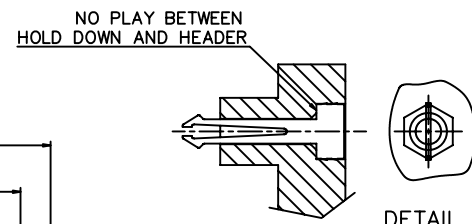
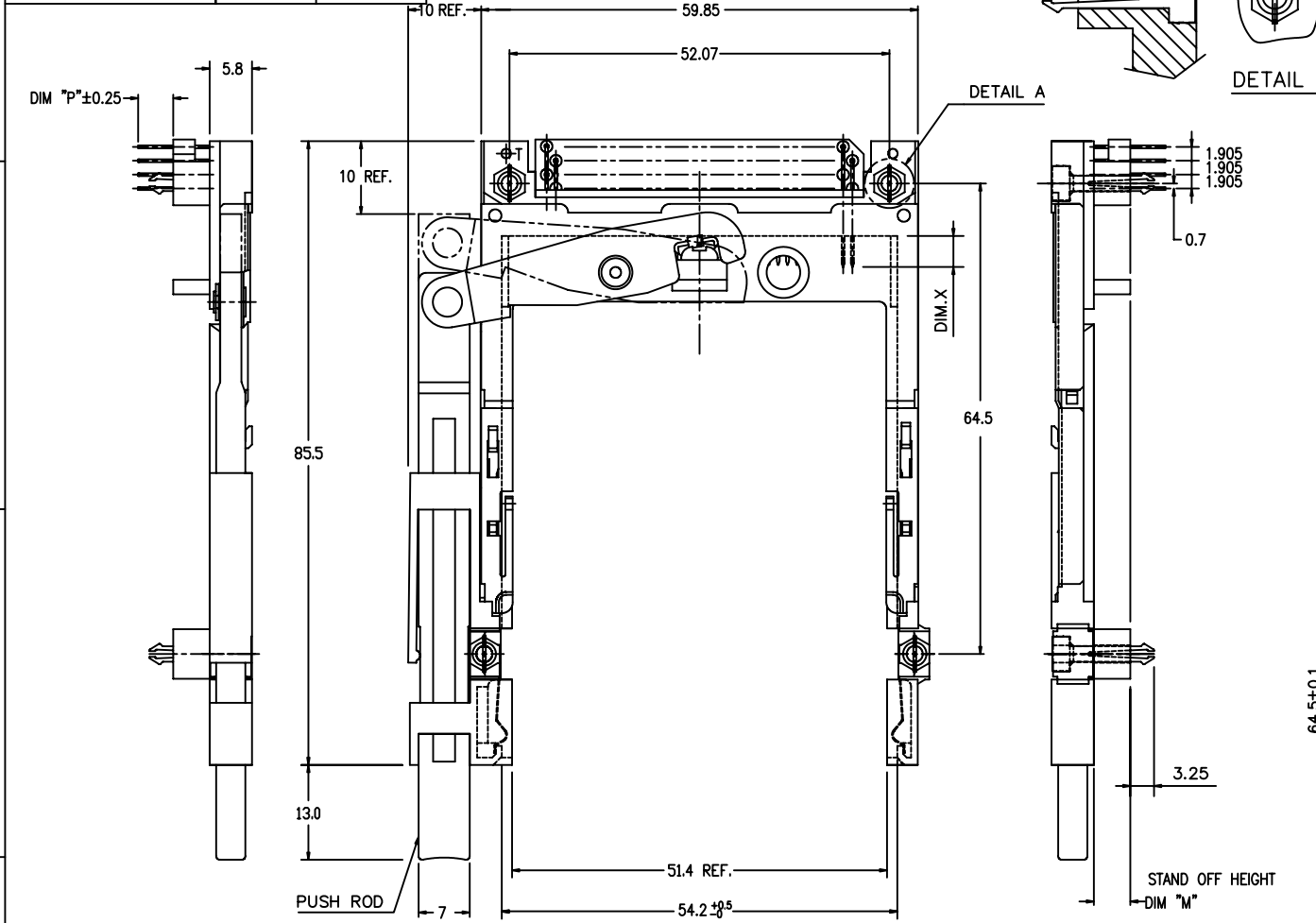


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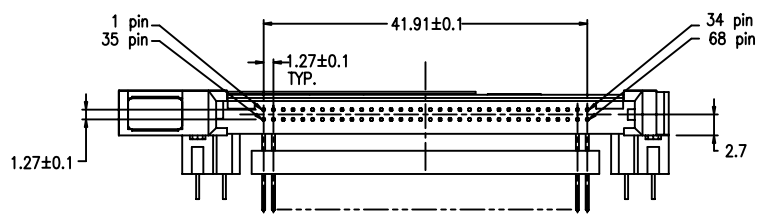
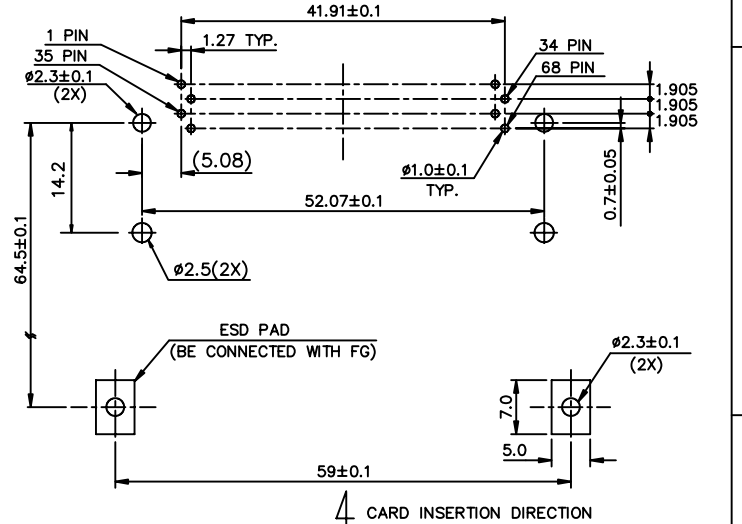
PRODUCT NO.	DIM "M"	DIM "P"
52581-130CAH	3	4.8
52581-150CAH	5	4.8
52581-130CAHLF	3	4.8
52581-150CAHLF	5	4.8



- NOTES:
- MATERIAL
 - HEADER ASS'Y:
 - PLASTIC : HOUSING ...LCP UL94V-0 BLACK
 - PIN : COPPER ALLOY
 - EJECT MECHANISM ASS'Y:
 - PLASTIC : GUIDE: POLYPHTHARAMID, BLACK
 - : PUSH ROD: POLYPHTHARAMID, BLACK
 - PLATE : STAINLESS
 - EMI CONTACT: PHOSPHOR BRONZE
 - FINISH (PIN)
 - UNDER PLATING : 0.5 um MIN. Ni
 - CONTACT AREA : 0.1 um MIN. GOLD OVER
 - : 0.5 um MIN. Pd-Ni
 - SOLDER TAIL : 2.5 um MIN. Sn-Pb
 - : 2.5 um MIN. PURE Sn (FOR -*****LF)

3. DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68	

- RETENTION FORCE HOLD DOWN VERSUS HEADER: 15N MIN.
- P.C.B. THICKNESS 1.6mm.
- IF LEAD FREE P/N THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com		
rev.	ecn no.	dr	date	linear	±0.30	projection	title	
A	T00288	W L	09/21/00				SINGLE DECK,R/A EJECTOR	
B	T03-0326	W L	08/14/03				TYPE I/II/III	
C	N05-0135	W B	05/27/05	angles	± 2°			
		dr	WENDY CHEN	01/19/00	unit	product family		
		enr	LEIF SHEN	01/19/00	mm/inch	size	PCMDA	
		chr	JOSEPH HSIAO	01/19/00	scale	dwg no.	code	
		appd	LELAND WANG	01/19/00	1:1	A3	52581	
sheet	revision							sheet
index	sheet							1 of 1